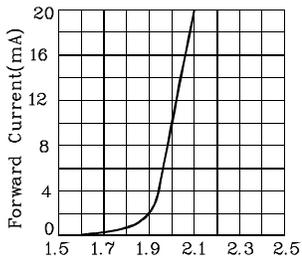
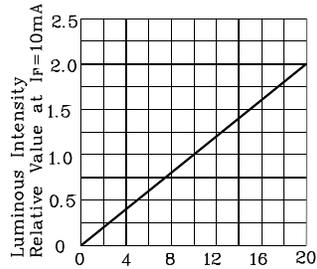


Relative Intensity Vs. CIE Wavelength

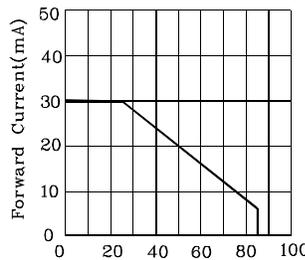
◆ Green



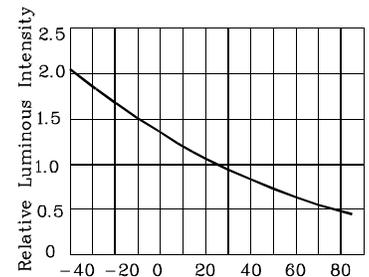
Forward Voltage(V)
FORWARD CURRENT Vs
FORWARD VOLTAGE



If - Forward Current (mA)
LUMINOUS INTENSITY Vs.
FORWARD CURRENT



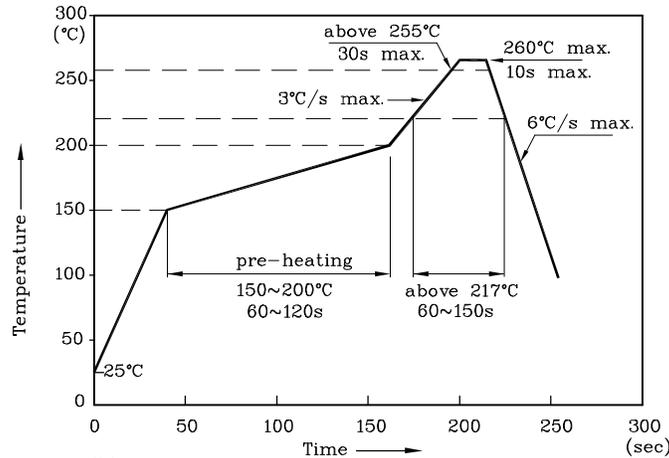
Ambient Temperature Ta(°C)
FORWARD CURRENT
DERATING CURVE



Ambient Temperature Ta(°C)
LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE

LED is recommended for reflow soldering and soldering profile is shown below.

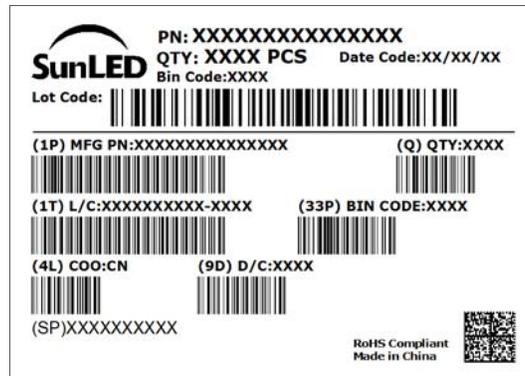
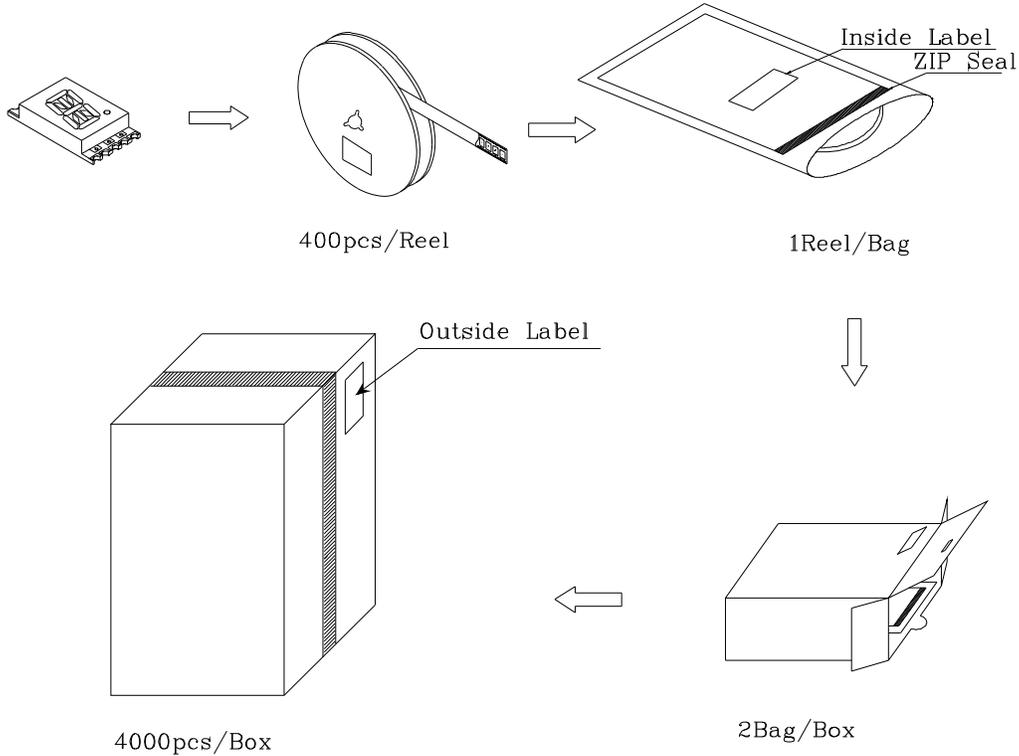
Reflow Soldering Profile for SMD Products (Pb-Free Components)



Notes:

1. All temperatures refer to the center of the package, measured on the package body surface facing up during reflow.
2. Do not apply any stress to the LED during high temperature conditions.
3. Maximum number of soldering passes: 2

PACKING & LABEL SPECIFICATIONS



TERMS OF USE

1. Data presented in this document reflect statistical figures and should be treated as technical reference only.
2. Contents within this document are subject to improvement and enhancement changes without notice.
3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet.
User accepts full risk and responsibility when operating the product(s) beyond their intended specifications.
4. The product(s) described in this document are intended for electronic applications in which a person's life is not reliant upon the LED. Please consult with a SunLED representative for special applications where the LED may have a direct impact on a person's life.
5. The contents within this document may not be altered without prior consent by SunLED.
6. When any special process such as potting is required for LED assembly, please consult with SunLED representative before proceeding.
7. Additional technical notes are available at <https://www.SunLEDusa.com/TechnicalNotes.asp>